

PDM: Rev:L

STATUS: Released

Printed: Sep 18, 2008

4 1|2 3 PRODUCT NUMBER DIM LENGTH FORMULAS (SEE NOTE 10) DIM "A' 51742-ABBCCC00EF__ 100 [2.54] x (CCC/4) + .250 [6.35] x BB + .650 [16.51] (NOTE 10) NOTE:(1) DIM "B' .100 [2.54] x (CCC/4) + .250 [6.35] x BB + .350 [8.89] DIM "C' 100 [2.54] x (CCC/4) + .250 [6.35] x BB + .300 [7.62] DIM "F" 100 [2.54] x (CCC/4) + .450 [11.43] ication propiet DIM "F' .100 [2.54] x (CCC/4) + .250 [6.35] x BB + .680 [17.27] 들귱 DIM "H' 100 [2.54] x (CCC/4) + .250 [6.35] u comr ecrite CONNECTOR NOTES I PRODUCT NUMBER CODE: RETENTION TO PCB OPTIONS: 51742 - A BB CCC 00 E F LF A = BOARD LOCK (REQUIRES .098 + .002, -.001 NO THIS SUFFIX: 100 u "/2.54 um SnPb ON PCB INTERFACE [2 49 +0 05 -0 031 THRU HOLF IN PCB) ADD THIS SUFFIX: 78 u " / 2.00 um Sn ON PCB INTERFACE (NOT AVAILABLE WITH PRESS FIT) RETENTION TO PCB (NOTE 8) ves soit de BOARD LOCK TO BE USED IN CONJUNCTION WITH TAIL OPTIONS (NOTE 7) AN .092 PCB OR THICKER. ALWAYS '00' (ZERO, ZERO) (NOTE 6) C = NO RETENTION FEATURE (ALL PRESS FIT). NUMBER OF SIGNAL CONTACTS (NOTE 5) af a Ge NUMBER OF RIGHT POWER CONTACTS (NOTE 4) 9. MANUFACTURE'S NAME, P/N, AND DATE CODE -PLATING (NOTE 3) stricteme forme c FCI. TO APPEAR ON THIS SURFACE. -BASE NUMBER 10. THE MAXIMUM OVERALL LENGTH (DIM A) OF A PART droits s quelque iete de HOUSING MATERIAL: GLASS FILLED V-O HIGH TEMP THERMO PLASTIC. IS 8.00 [203.2]. SIGNAL CONTACT MATERIAL: COPPER ALLOY POWER CONTACT MATERIAL: COPPER ALLOY II. PRODUCT SPECIFICATION GS-12-149. Α 12. REFERENCE 51698 FOR SPECIALS WORKSHEET. SEE PRINT 10064183 FOR PLATING SPEC OF 51742-1BBCCC00EF; 51742-1BBCCC00EFLF Α 4. RIGHT END POWER CONTACT, OI TO 20 AVAILABLE. MAXIMUM OF 20 POWER CONTACTS PER CONNECTOR. 13. ALL DIMENSIONS ARE BASIC UNLESS OTHERWISE SPECIFIED. SIGNAL CONTACTS, 004 TO 148 AVAILABLE. 14. ALL THROUGH HOLES ARE LOCATED WITH A TRUE POSITION OF .004 [0.01] 6. THIS PART NOT AVAILABLE WITH LEFT SIDE POWER CONTACTS. 15. ALL HOLE DIAMETERS ARE FINISHED HOLE SIZE. 7. TAIL OPTIONS: 16. 0.0453±.001 [1.151±.02] DRILLED HOLES PLATED WITH 0.0003 [0.007] MIN SnPb OVER 0.001 [1.03] TO .003 [0.08] PLATING TO ACHIEVE A .040 ±.003 [1.02 ±.08] HOLE. A = .135 ±.010[3.43±.25] SOLDER TO BOARD in any propriet C = .135 ±.010[3.43±.25] PRESS FIT 17. THE VOID CORING IN BETWEEN POWER MODULES, SIGNAL MODULES AND END MODULES ARE OPTIONAL AND THE SHAPE MAY BE DIFFERENT FOR OPTIMIZING THE MOLDING ties The ĎΕ PROCESS. THE VOID CORING WILL NOT EFFECT TO PRODUCT FUNCTION. tion or issue to it written authorit 18. A

ASYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW, OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION tolerances unless mat'l code SEE NOTE 2 CUSTOMER reserved. Reproduction not permitted without copyright FCI. otherwise specified ecn no. dr dote XX±.01/0.X±0.3 COPY www.fciconnect.com projection linear .XXX±.005/0.XX±0.13 VERTICAL RECEPTACLE W/GUIDE PIN XXXX±.0020/.XXX±.051 POWER / SIGNAL angles $0^{\circ} \pm 2^{\circ}$ PWRBLADF code dr D. EATON 05-25-99 product family INCH/MM 213 engr J. BROWN 05-24-99 size dwg no trictly r ver is r FCI. chr J. BROWN 05-26-99 scale sheet 742 J. BROWN 05-26-99 2 of 3 All rights stric form whateve Property of F appd revision В В index sheet

Pro/E

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3

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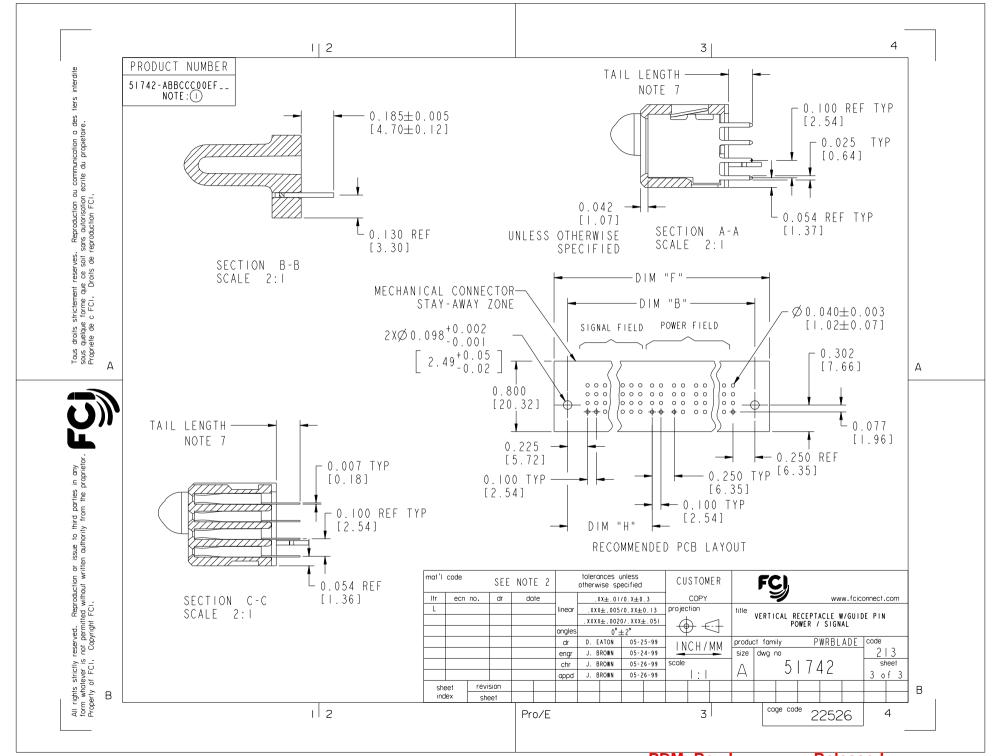
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